

SILICON GATE BiCMOS

65,536 WORD x 4 BIT BiCMOS STATIC RAM

Description

The TC55B465P/J is a 262,144 bit high speed BiCMOS static random access memory organized as 65,536 words by 4 bits and operated from a single 5V supply. Toshiba's BiCMOS technology and advanced circuit design enable high speed operation.

The TC55B465P/J features low power dissipation when the device is deselected using chip enable (\overline{CE}) and has an output enable input (\overline{OE}) for fast memory access.

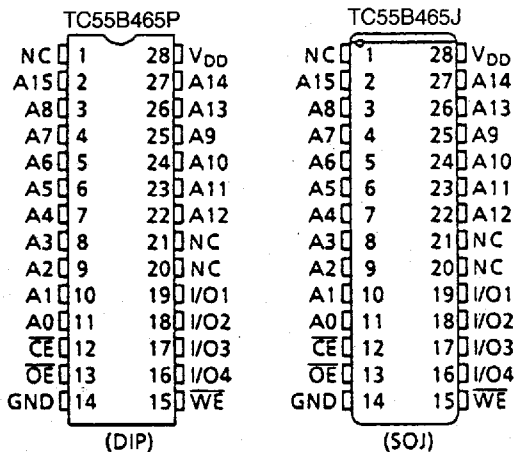
The TC55B465P/J is suitable for use in high speed applications such as cache memory and high speed storage. All inputs and outputs are TTL compatible.

The TC55B465P/J is available in a 300mil width, 28-pin DIP and SOJ suitable for high density surface assembly.

Features

- Fast access time
 - TC55B465P/J-10 10ns (max.)
 - TC55B465P/J-12 12ns (max.)
- Low power dissipation
 - Operation:
 - TC55B465P/J-10 140mA (max.)
 - TC55B465P/J-12 140mA (max.)
 - Standby: 15mA (max.)
- Single 5V power supply: 5V±10%
- Fully static operation
- Inputs and outputs TTL compatible
- Output buffer control: \overline{OE}
- Package:
 - TC55B465P: DIP28-P-300B
 - TC55B465J: SOJ28-P-300A

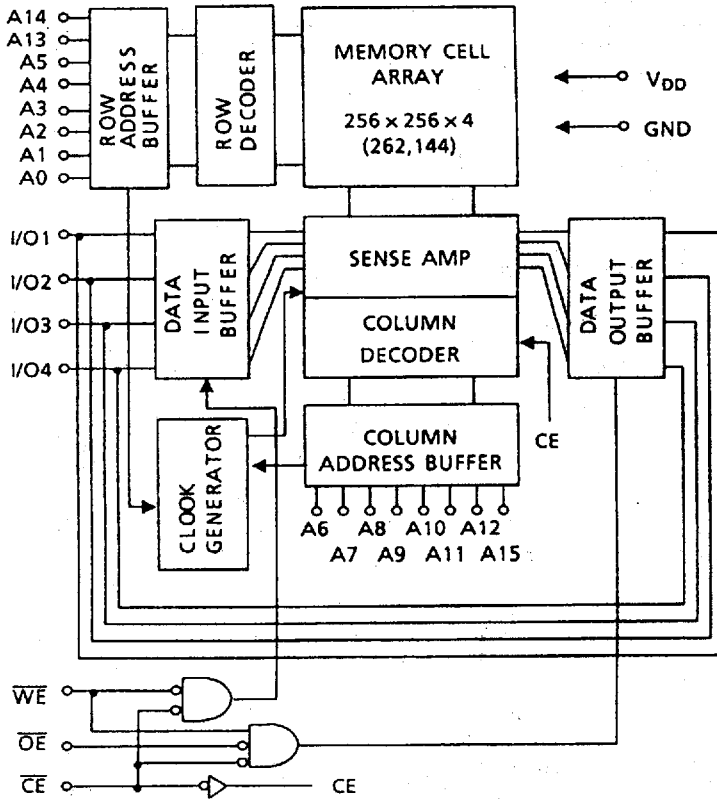
Pin Connection (Top View)



Pin Names

A0 ~ A15	Address Inputs
I/O1 ~ I/O4	Data Inputs/Outputs
\overline{CE}	Chip Enable Input
\overline{WE}	Write Enable Input
\overline{OE}	Output Enable Input
V _{DD}	Power (+5V)
GND	Ground
NC	No Connection

Block Diagram



Operating Mode

MODE	PIN	\overline{CE}	\overline{OE}	\overline{WE}	I/O1 ~ I/O4	POWER
Read		L	L	H	Output	I_{DDO}
Write		L	*	L	Input	I_{DDO}
Output Disable		L	H	H	High Impedance	I_{DDO}
Standby		H	*	*	High Impedance	I_{DDs}

*H or L

Maximum Ratings

SYMBOL	ITEM	RATING	UNIT
V_{DD}	Power Supply Voltage	-0.5 ~ 7.0	V
V_{IN}	Input Voltage	-2.0 ~ 7.0	V
V_{IO}	Input/Output Voltage	-0.5* ~ $V_{DD} + 0.5$	V
P_D	Power Dissipation	1.0	W
T_{SOLDER}	Soldering Temperature • Time	260 • 10	°C • sec
T_{STRG}	Storage Temperature	-65 ~ 150	°C
T_{OPR}	Operating Temperature	-10 ~ 85	°C

*-3V with a pulse width of 10ns

DC Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{DD}	Power Supply Voltage	4.5	5.0	5.5	V
V _{IH}	Input High Voltage	2.2	–	V _{DD} + 0.5	V
V _{IL}	Input Low Voltage	-0.5*	–	0.8	V

* -3V with a pulse width of 10ns

DC Characteristics (Ta = 0 ~ 70°C, V_{DD} = 5V±10%)

SYMBOL	PARAMETER	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
I _{LI}	Input Leakage Current	V _{IN} = 0 ~ V _{DD}	–	–	±10	μA
I _{LO}	Output Leakage Current	$\overline{CE} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$, V _{OUT} = 0 ~ V _{DD}	–	–	±10	μA
I _{OH}	Output High Current	V _{OH} = 2.4V	-4	–	–	mA
I _{OL}	Output Low Current	V _{OL} = 0.4V	8	–	–	mA
I _{DDO}	Operating Current	t _{cycle} = Min cycle CE = V _{IL} Other Inputs = V _{IH} /V _{IL} , I _{OUT} = 0mA	–	–	140	mA
I _{DDS1}	Standby Current	$\overline{CE} = V_{IH}$ Other Inputs = V _{IH} /V _{IL}	–	–	30	mA
I _{DDS2}		$\overline{CE} = V_{DD} - 0.2V$ Other Inputs = V _{DD} - 0.2V or 0.2V	–	–	15	

Capacitance* (Ta = 25°C, f = 1.0MHz)

SYMBOL	PARAMETER	TEST CONDITION	MAX.	UNIT
C _{IN}	Input Capacitance	V _{IN} = GND	6	pF
C _{I/O}	Input/Output Capacitance	V _{I/O} = GND	8	pF

*This parameter is periodically sampled and is not 100% tested.

AC Characteristics (Ta = 0 ~ 70°C⁽¹⁾, V_{DD} = 5V±10%)

Read Cycle

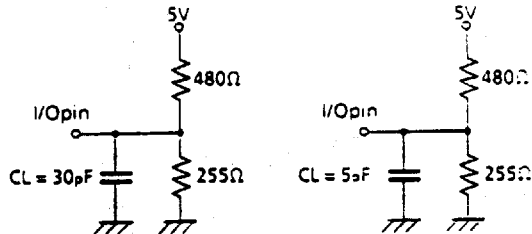
SYMBOL	PARAMETER	TC55B465P/J-10		TC55B465P/J-12		UNIT
		MIN.	MAX.	MIN.	MAX.	
t _{RC}	Read Cycle Time	10	—	12	—	ns
t _{ACC}	Address Access Time	—	10	—	12	
t _{CO}	\overline{CE} Access Time	—	10	—	12	
t _{OE}	\overline{OE} Access Time	—	5	—	6	
t _{OH}	Output Data Hold Time from Address Change	3	—	3	—	
t _{COE}	Output Enable Time from \overline{CE}	3	—	3	—	
t _{COD}	Output Disable Time from \overline{CE}	—	5	—	6	
t _{OEE}	Output Enable Time from \overline{OE}	1	—	1	—	
t _{ODO}	Output Disable Time from \overline{OE}	—	5	—	6	
t _{PU}	Chip Selection to Power Up Time	0	—	0	—	
t _{PD}	Chip Deselection to Power Down Time	—	10	—	12	

Write Cycle

SYMBOL	PARAMETER	TC55B465P/J-10		TC55B465P/J-12		UNIT
		MIN.	MAX.	MIN.	MAX.	
t _{WC}	Write Cycle Time	10	—	12	—	ns
t _{CW}	Chip Enable to End of Write	7	—	8	—	
t _{AS}	Address Setup Time	0	—	0	—	
t _{AW}	Address Valid to End of Write	7	—	8	—	
t _{WP}	Write Pulse Width	6	—	7	—	
t _{WR}	Write Recovery Time	1	—	1	—	
t _{DS}	Data Setup Time	6	—	7	—	
t _{DH}	Data Hold Time	0	—	0	—	
t _{OE_W}	Output Enable Time from \overline{WE}	1	—	1	—	
t _{ODW}	Output Disable Time from \overline{WE}	—	5	—	6	

AC Test Conditions

Input Pulse Levels	3.0V/0.0V
Input Pulse Rise and Fall Time	3ns
Input Timing Measurement Reference Levels	1.5V
Output Timing Measurement Reference Levels	1.5V
Output Load	Fig. 1

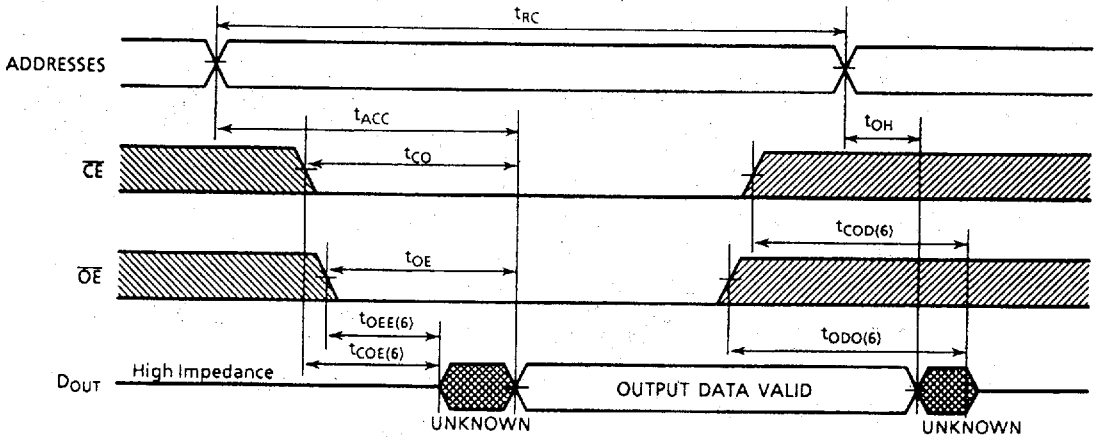


(For t_{COE}, t_{OEE}, t_{COD}, t_{ODO}, t_{OE_W} and t_{ODW})

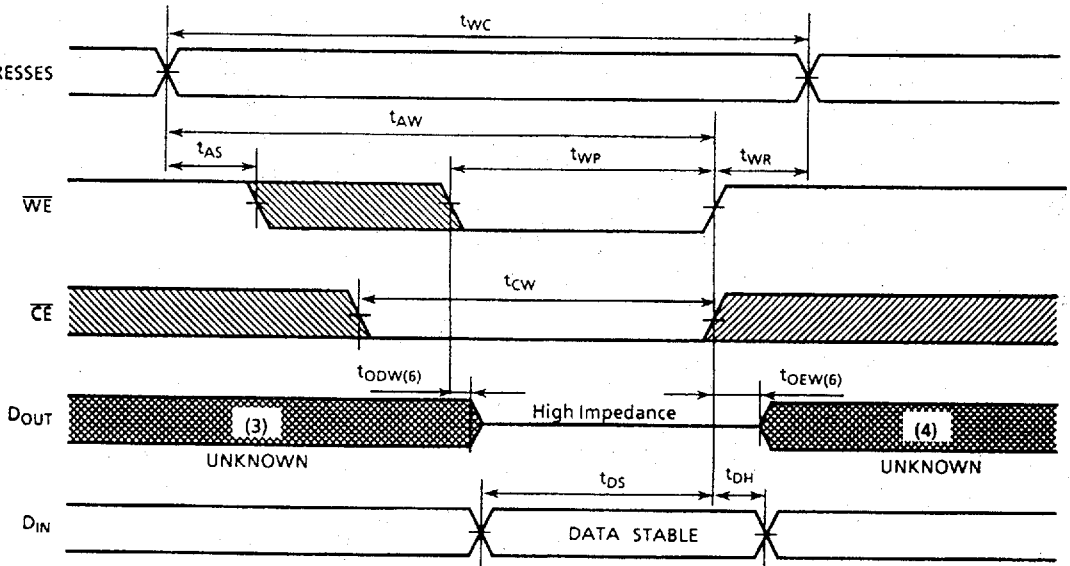
Figure 1.

Timing Waveforms

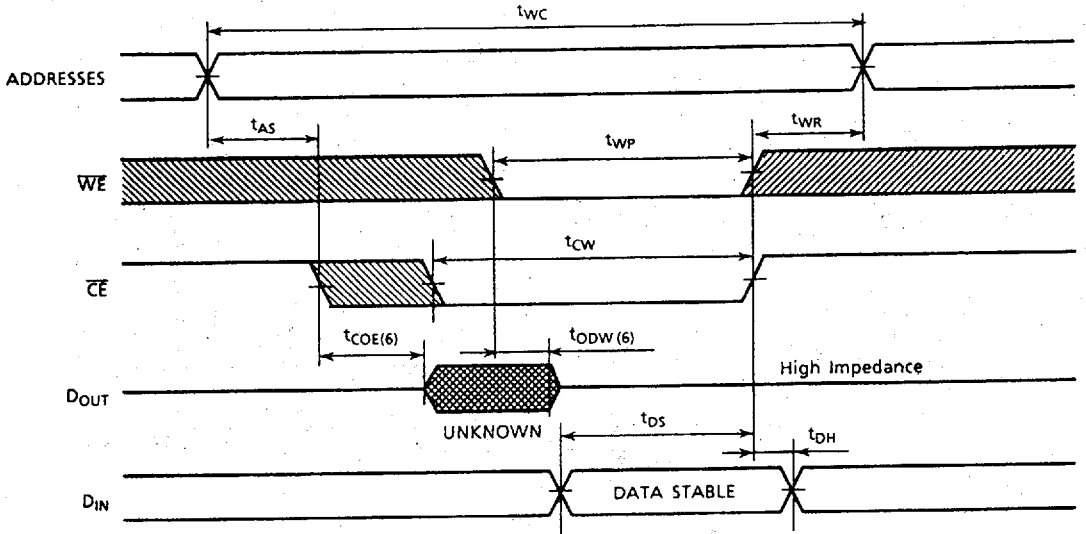
Read Cycle ⁽²⁾



Write Cycle 1 ⁽⁵⁾ (\overline{WE} Controlled Write)



Write Cycle 2 ⁽⁵⁾ (\overline{CE} Controlled Write)



Notes:

1. The operating temperature (T_a) is guaranteed with transverse air flow exceeding 400 linear feet per minute.
2. \overline{WE} is high for read cycles.
3. If the \overline{CE} low transition occurs coincident with or after the \overline{WE} low transition, outputs remain in a high impedance state.
4. If the \overline{CE} high transition occurs coincident with or prior to the \overline{WE} high transition, outputs remain in a high impedance state.
5. If \overline{OE} is high during a write cycle, the outputs are in a high impedance state during this period.
6. The following parameters are measured using the load shown in Fig. 1.
 - (A) t_{COE} , t_{OEE} , $t_{OE\overline{W}}$ Output Enable Time
 - (B) t_{COD} , t_{ODO} , $t_{OD\overline{W}}$ Output Disable Time

